



SOT226B

Plastic single-ended package (I2PAK); low-profile 3-lead
TO-262

13 July 2016

Package information

1. Package summary

Dimensions (mm)	11 x 10 x 4.5
Terminal position code	S (single)
Package type descriptive code	I2PAK
Package outline version code	SOT226B
Manufacturer package code	SOT226
Package type industry code	I2PAK
Package outline version description	Plastic single-ended package (I2PAK); low-profile 3-lead TO-262
Package style descriptive code	SIP (single in-line package)
Package body material type	P
Handling precautions	IC26_CHAPTER_3_2000
Thermal design considerations	SC18_1999_CHAPTER_5_2
Mounting method type	T (through-hole mount)
Generic mounting and soldering information	SC18_2004_CHAPTER_4_3
Major version date	24-10-2012
Minor version date	24-10-2012
Security status	COMPANY PUBLIC
Modified date	29-10-2012
Issue date	8-6-2016
Web publication date	28-11-2012
Initial web publication date	24-10-2012
Customer specific indicator	N
Maturity	Product

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
A ₂	package height		-	-	-	-	
A	seated height		4.1	-	4.3	4.5	mm
D	package length		-	-	-	11	mm
E	package width		9.7	-	-	10.3	mm
e	nominal pitch		-	-	2.54	-	mm
n ₂	actual quantity of termination		-	-	3	-	



2. Package outline

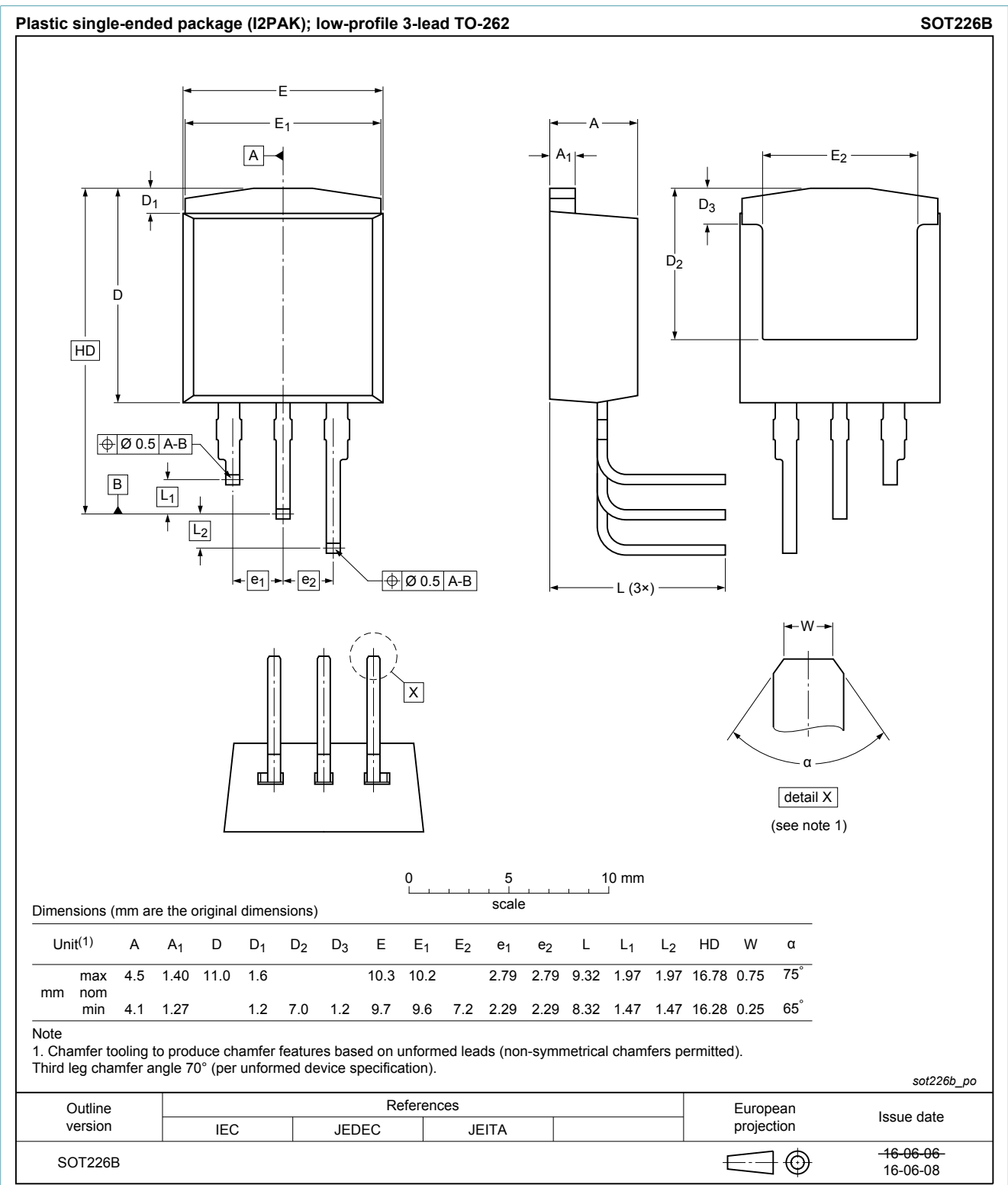


Fig. 1. Package outline I2PAK (SOT226B)

3. Legal information

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